

## P-Channel Enhancement Mode Power MOSFET

## **Description**

The HM4443 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , This device is suitable for use as a load switch and battery protection applications.

#### **General Features**

•  $V_{DS} = -40V, I_{D} = -6.0A$ 

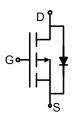
 $R_{DS(ON)}$  < 126m $\Omega$  @  $V_{GS}$ =-4.5V

 $R_{DS(ON)}$  < 85m $\Omega$  @  $V_{GS}$ =-10V

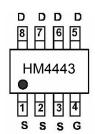
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

## **Application**

- Battery applications
- Load switch



#### Schematic diagram



Marking and pin assignment



SOP-8 top view

## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
HM4443	HM4443	SOP-8	Ø180mm	8 mm	3000 units

## Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	-40	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	-6.0	Α
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	-24	Α
Maximum Power Dissipation	P <sub>D</sub>	2.0	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$ C

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2) R <sub>BJA</sub> 62.5
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## **Electrical Characteristics (T<sub>A</sub>=25 ℃ unless otherwise noted)**

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-40V,V <sub>GS</sub> =0V	-	-	-1	μΑ



Parameter	Symbol	Condition	Min	Тур	Max	Unit
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)	·		•	•		
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA		-1.5	-3	V
Drain-Source On-State Resistance	Б	V <sub>GS</sub> =-10V, I <sub>D</sub> =-5A -		73	85	mΩ
	$R_{DS(ON)}$	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-4A -		98	126	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =-5V,I <sub>D</sub> =-4.1A	10	-	-	S
Dynamic Characteristics (Note4)	•		•	•		
Input Capacitance	C <sub>lss</sub>	\/ 00\/\\ 0\/	-	650	-	PF
Output Capacitance	Coss	$V_{DS}$ =-20V, $V_{GS}$ =0V, F=1.0MHz	-	90	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVID2	-	70	-	PF
Switching Characteristics (Note 4)				•		
Turn-on Delay Time	t <sub>d(on)</sub>		-	9	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-20 $V$ , $R_L$ =2 $\Omega$	-	8	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10V, $R_{GEN}$ =3 $\Omega$	-	28	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Qg	\/ - 20\/   - 2.14	-	14	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =-20V, $I_{D}$ =-3.1A, $V_{GS}$ =-10V	-	2.9	-	nC
Gate-Drain Charge	$Q_{gd}$	v <sub>GS</sub> 10v	-	3.8	-	nC
Drain-Source Diode Characteristics	•			•		
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-2.5A	-	8.0	1.2	V
Diode Forward Current (Note 2)	Is		-	-	-5.3	Α

## Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production



# **Typical Electrical and Thermal Characteristics**

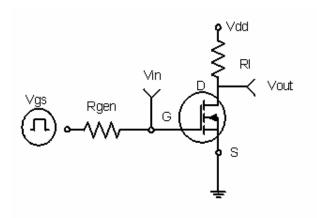


Figure 1:Switching Test Circuit

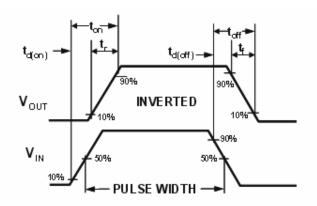
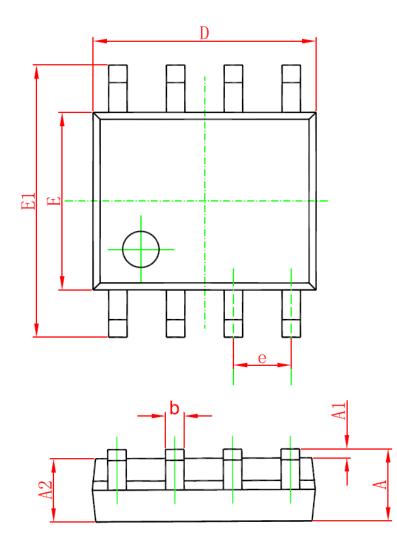
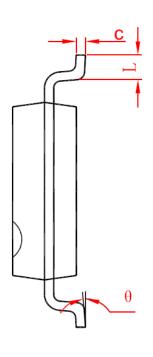


Figure 2:Switching Waveforms



## **SOP8 PACKAGE OUTLINE DIMENSIONS**





Cl	Dimensions Ir	n Millimeters	Dimensions In Inches			
Symbol	Min	Max	Min	Max		
Α	1. 350	1. 750	0. 053	0.069		
A1	0. 100	0. 250	0. 004	0. 010		
A2	1. 350	1. 550	0. 053	0. 061		
b	0. 330	0. 510	0. 013	0. 020		
С	0. 170	0. 250	0. 006	0. 010		
D	4. 700	5. 100	0. 185	0. 200		
Е	3.800	4. 000	0. 150	0. 157		
E1	5. 800	6. 200	0. 228	0. 244		
е	1. 270	(BSC)	0. 050	0. 050 (BSC)		
L	0. 400	1. 270	0. 016	0.050		
θ	0°	8°	0°	8°		

Page 4



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